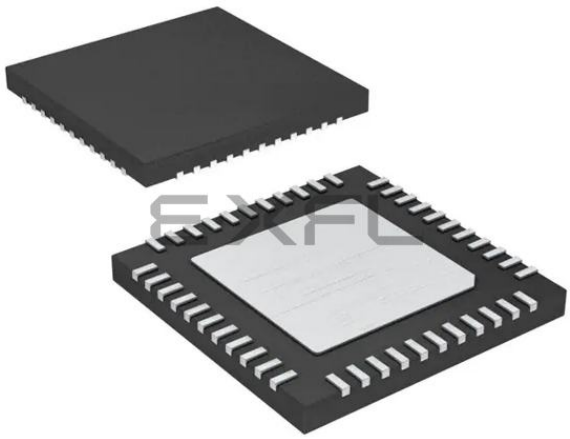
Microchip Technology - PIC32MX270F256DT-V/ML Datasheet



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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	MIPS32® M4K™
Core Size	32-Bit Single-Core
Speed	40MHz
Connectivity	I²C, IrDA, LINbus, SPI, UART/USART, USB OTG
Peripherals	Brown-out Detect/Reset, DMA, I²S, POR, PWM, WDT
Number of I/O	33
Program Memory Size	256KB (256K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	64K x 8
Voltage - Supply (Vcc/Vdd)	2.3V ~ 3.6V
Data Converters	A/D 13x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Surface Mount
Package / Case	44-VQFN Exposed Pad
Supplier Device Package	44-QFN (8x8)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic32mx270f256dt-v-ml

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3.0 CPU

Note: This data sheet summarizes the features of the PIC32MX1XX/2XX 28/36/44-pin Family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 2. "CPU"** (DS60001113), which is available from the *Documentation > Reference Manual* section of the Microchip PIC32 web site (www.microchip.com/pic32). Resources for the MIPS32® M4K® Processor Core are available at: www.imgtec.com.

The MIPS32® M4K® Processor Core is the heart of the PIC32MX1XX/2XX family processor. The CPU fetches instructions, decodes each instruction, fetches source operands, executes each instruction and writes the results of instruction execution to the destinations.

3.1 Features

- 5-stage pipeline
- 32-bit address and data paths
- MIPS32 Enhanced Architecture (Release 2)
  - Multiply-accumulate and multiply-subtract instructions
  - Targeted multiply instruction
  - Zero/One detect instructions
  - `WAIT` instruction
  - Conditional move instructions (`MOVN`, `MOVZ`)
  - Vectored interrupts
  - Programmable exception vector base
  - Atomic interrupt enable/disable
  - Bit field manipulation instructions
- MIPS16e® code compression
  - 16-bit encoding of 32-bit instructions to improve code density
  - Special PC-relative instructions for efficient loading of addresses and constants
  - `SAVE` and `RESTORE` macro instructions for setting up and tearing down stack frames within subroutines
  - Improved support for handling 8 and 16-bit data types
- Simple Fixed Mapping Translation (FMT) mechanism
- Simple dual bus interface
  - Independent 32-bit address and data buses
  - Transactions can be aborted to improve interrupt latency
- Autonomous multiply/divide unit
  - Maximum issue rate of one 32x16 multiply per clock
  - Maximum issue rate of one 32x32 multiply every other clock
  - Early-in iterative divide. Minimum 11 and maximum 33 clock latency (dividend (*rs*) sign extension-dependent)
- Power control
  - Minimum frequency: 0 MHz
  - Low-Power mode (triggered by `WAIT` instruction)
  - Extensive use of local gated clocks
- EJTAG debug and instruction trace
  - Support for single stepping
  - Virtual instruction and data address/value
  - Breakpoints

FIGURE 3-1: MIPS32® M4K® PROCESSOR CORE BLOCK DIAGRAM

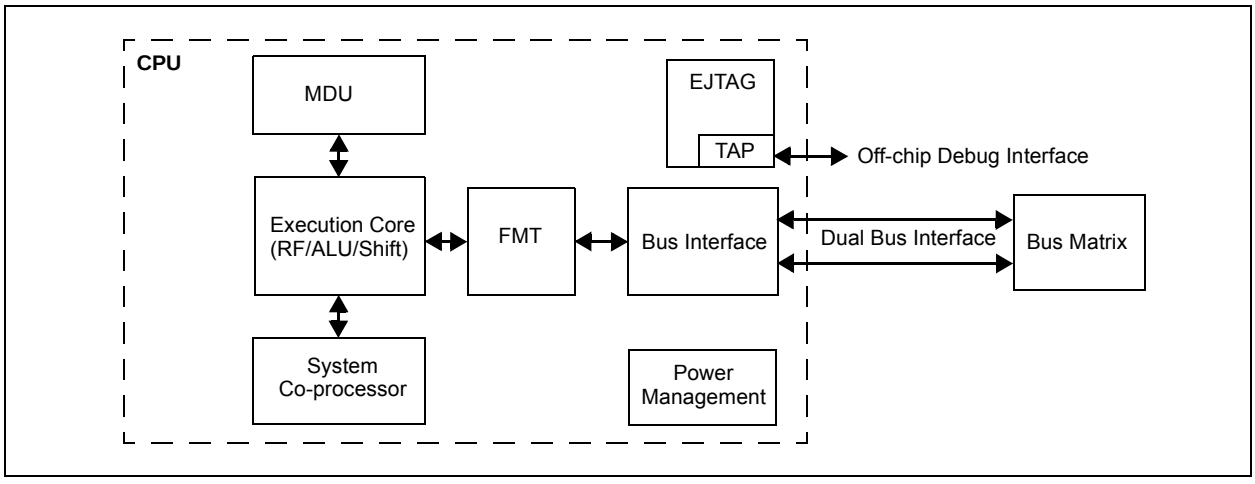
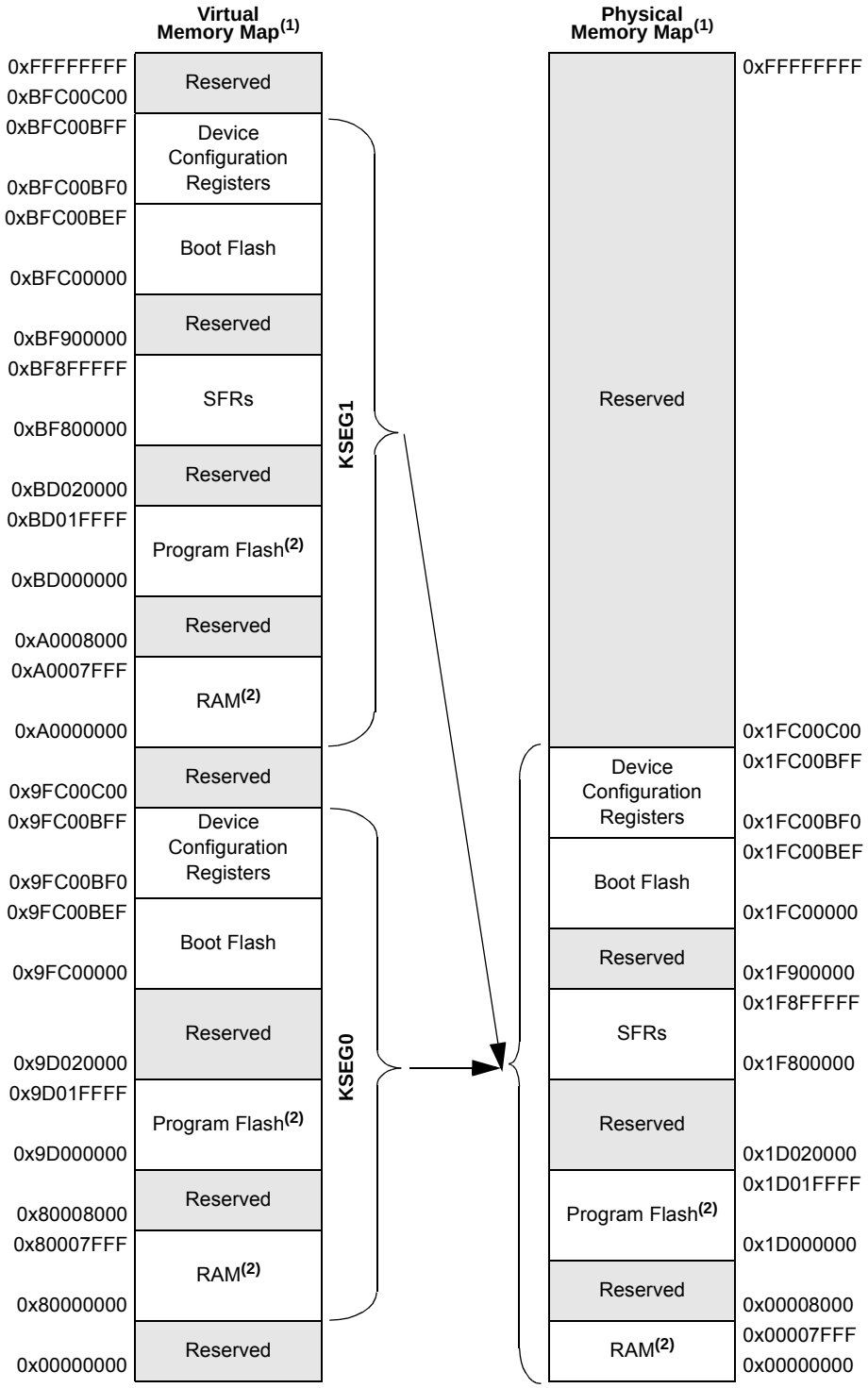


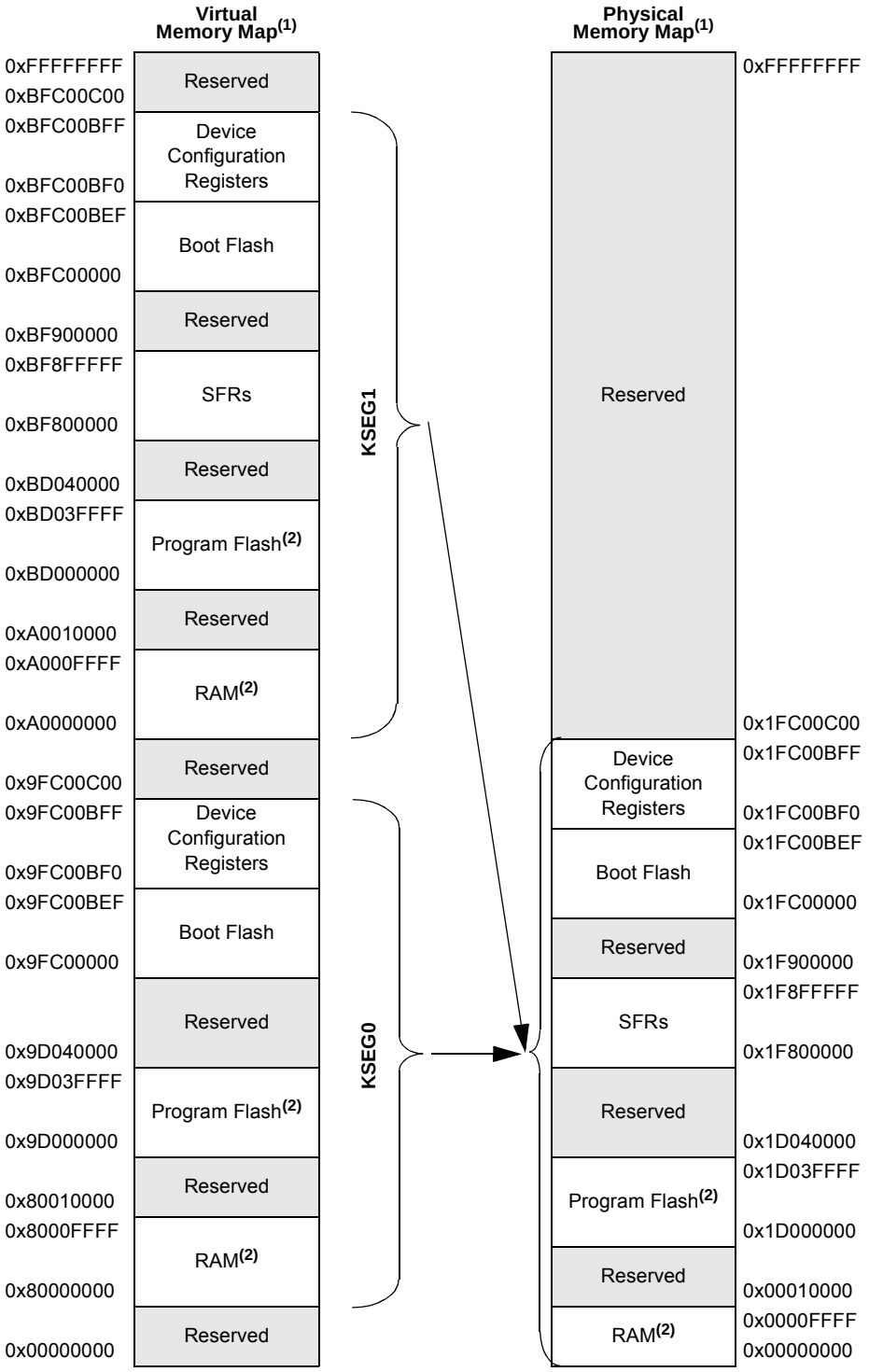
FIGURE 4-4: MEMORY MAP ON RESET FOR PIC32MX150/250 DEVICES (32 KB RAM, 128 KB FLASH)



Note 1: Memory areas are not shown to scale.

2: The size of this memory region is programmable (see **Section 3. "Memory Organization"** (DS60001115) in the *"PIC32 Family Reference Manual"*) and can be changed by initialization code provided by end-user development tools (refer to the specific development tool documentation for information).

FIGURE 4-5: MEMORY MAP ON RESET FOR PIC32MX170/270 DEVICES (64 KB RAM, 256 KB FLASH)



Note 1: Memory areas are not shown to scale.

2: The size of this memory region is programmable (see **Section 3. "Memory Organization"** (DS60001115) in the *"PIC32 Family Reference Manual"*) and can be changed by initialization code provided by end-user development tools (refer to the specific development tool documentation for information).

REGISTER 4-2: BMXDKPBA: DATA RAM KERNEL PROGRAM BASE ADDRESS REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R-0	R-0
	BMXDKPBA<15:8>							
7:0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0
	BMXDKPBA<7:0>							

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-16 **Unimplemented:** Read as '0'

bit 15-10 **BMXDKPBA<15:10>:** DRM Kernel Program Base Address bits
When non-zero, this value selects the relative base address for kernel program space in RAM

bit 9-0 **BMXDKPBA<9:0>:** Read-Only bits
This value is always '0', which forces 1 KB increments

Note 1: At Reset, the value in this register is forced to zero, which causes all of the RAM to be allocated to Kernal mode data usage.

2: The value in this register must be less than or equal to BMXDRMSZ.

REGISTER 4-4: BMXDUPBA: DATA RAM USER PROGRAM BASE ADDRESS REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R-0	R-0
	BMXDUPBA<15:8>							
7:0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0
	BMXDUPBA<7:0>							

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-16 **Unimplemented:** Read as '0'

bit 15-10 **BMXDUPBA<15:10>:** DRM User Program Base Address bits

When non-zero, the value selects the relative base address for User mode program space in RAM, BMXDUPBA must be greater than BMXDUDBA.

bit 9-0 **BMXDUPBA<9:0>:** Read-Only bits

This value is always '0', which forces 1 KB increments

Note 1: At Reset, the value in this register is forced to zero, which causes all of the RAM to be allocated to Kernal mode data usage.

2: The value in this register must be less than or equal to BMXDRMSZ.

REGISTER 6-2: RSWRST: SOFTWARE RESET REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
7:0	U-0	U-0	U-0	U-0	U-0	U-0	U-0	W-0, HC
	—	—	—	—	—	—	—	SWRST(1)

Legend:	HC = Cleared by hardware		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-1 **Unimplemented:** Read as '0'

bit 0 **SWRST:** Software Reset Trigger bit(1)
- 1 = Enable Software Reset event
- 0 = No effect

Note 1: The system unlock sequence must be performed before the SWRST bit is written. Refer to **Section 6. "Oscillator"** (DS60001112) in the *"PIC32 Family Reference Manual"* for details.

8.0 OSCILLATOR CONFIGURATION

Note: This data sheet summarizes the features of the PIC32MX1XX/2XX 28/36/44-pin Family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 6. "Oscillator Configuration"** (DS60001112), which is available from the *Documentation > Reference Manual* section of the Microchip PIC32 web site (www.microchip.com/pic32).

The PIC32MX1XX/2XX 28/36/44-pin Family oscillator system has the following modules and features:

- Four external and internal oscillator options as clock sources
- On-Chip PLL with user-selectable input divider, multiplier and output divider to boost operating frequency on select internal and external oscillator sources
- On-Chip user-selectable divisor postscaler on select oscillator sources
- Software-controllable switching between various clock sources
- A Fail-Safe Clock Monitor (FSCM) that detects clock failure and permits safe application recovery or shutdown
- Dedicated On-Chip PLL for USB peripheral

A block diagram of the oscillator system is provided in Figure 8-1.

REGISTER 8-2: OSCTUN: FRC TUNING REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	R-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	U-0	R-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
7:0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	—	—	TUN<5:0>(1)					

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-6 **Unimplemented:** Read as '0'

bit 5-0 **TUN<5:0>:** FRC Oscillator Tuning bits(1)

100000 = Center frequency -12.5%
100001 =
•
•
•
111111 =
000000 = Center frequency. Oscillator runs at minimal frequency (8 MHz)
000001 =
•
•
•
011110 =
011111 = Center frequency +12.5%

Note 1: OSCTUN functionality has been provided to help customers compensate for temperature effects on the FRC frequency over a wide range of temperatures. The tuning step size is an approximation, and is neither characterized, nor tested.

Note: Writes to this register require an unlock sequence. Refer to **Section 6. "Oscillator"** (DS60001112) in the *"PIC32 Family Reference Manual"* for details.

REGISTER 11-3: CNCONx: CHANGE NOTICE CONTROL FOR PORTx REGISTER (x = A, B, C)

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	R/W-0	U-0	R/W-0	U-0	U-0	U-0	U-0	U-0
	ON	—	SIDL	—	—	—	—	—
7:0	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-16 **Unimplemented:** Read as '0'

bit 15 **ON:** Change Notice (CN) Control ON bit
- 1 = CN is enabled
- 0 = CN is disabled

bit 14 **Unimplemented:** Read as '0'

bit 13 **SIDL:** Stop in Idle Control bit
- 1 = Idle mode halts CN operation
- 0 = Idle does not affect CN operation

bit 12-0 **Unimplemented:** Read as '0'

NOTES:

REGISTER 22-3: AD1CON3: ADC CONTROL REGISTER 3

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	R/W-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	ADRC	—	—	SAMC<4:0>(1)				
7:0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W	R/W-0
	ADCS<7:0>(2)							

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-16 **Unimplemented:** Read as '0'

bit 15 **ADRC:** ADC Conversion Clock Source bit
1 = Clock derived from FRC
0 = Clock derived from Peripheral Bus Clock (PBCLK)

bit 14-13 **Unimplemented:** Read as '0'

bit 12-8 **SAMC<4:0>:** Auto-Sample Time bits(1)
11111 = 31 TAD
•
•
•
00001 = 1 TAD
00000 = 0 TAD (Not allowed)

bit 7-0 **ADCS<7:0>:** ADC Conversion Clock Select bits(2)
11111111 = TPB • 2 • (ADCS<7:0> + 1) = 512 • TPB = TAD
•
•
•
00000001 = TPB • 2 • (ADCS<7:0> + 1) = 4 • TPB = TAD
00000000 = TPB • 2 • (ADCS<7:0> + 1) = 2 • TPB = TAD

Note 1: This bit is only used if the SSRC<2:0> bits (AD1CON1<7:5>) = 111.
2: This bit is not used if the ADRC (AD1CON3<15>) bit = 1.

27.3 On-Chip Voltage Regulator

All PIC32MX1XX/2XX 28/36/44-pin Family devices' core and digital logic are designed to operate at a nominal 1.8V. To simplify system designs, most devices in the PIC32MX1XX/2XX 28/36/44-pin Family family incorporate an on-chip regulator providing the required core logic voltage from VDD.

A low-ESR capacitor (such as tantalum) must be connected to the VCAP pin (see Figure 27-1). This helps to maintain the stability of the regulator. The recommended value for the filter capacitor is provided in **Section 30.1 "DC Characteristics"**.

Note:	It is important that the low-ESR capacitor is placed as close as possible to the VCAP pin.

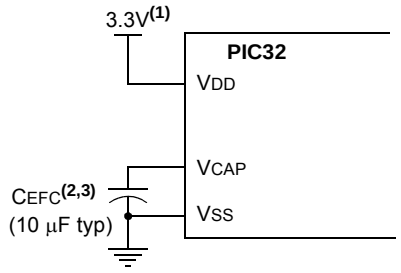
27.3.1 ON-CHIP REGULATOR AND POR

It takes a fixed delay for the on-chip regulator to generate an output. During this time, designated as TPU, code execution is disabled. TPU is applied every time the device resumes operation after any power-down, including Sleep mode.

27.3.2 ON-CHIP REGULATOR AND BOR

PIC32MX1XX/2XX 28/36/44-pin Family devices also have a simple brown-out capability. If the voltage supplied to the regulator is inadequate to maintain a regulated level, the regulator Reset circuitry will generate a Brown-out Reset. This event is captured by the BOR flag bit (RCON<1>). The brown-out voltage levels are specific in **Section 30.1 "DC Characteristics"**.

FIGURE 27-1: CONNECTIONS FOR THE ON-CHIP REGULATOR



Note 1: These are typical operating voltages. Refer to **Section 30.1 "DC Characteristics"** for the full operating ranges of VDD.

2: It is important that the low-ESR capacitor is placed as close as possible to the VCAP pin.

3: The typical voltage on the VCAP pin is 1.8V.

27.4 Programming and Diagnostics

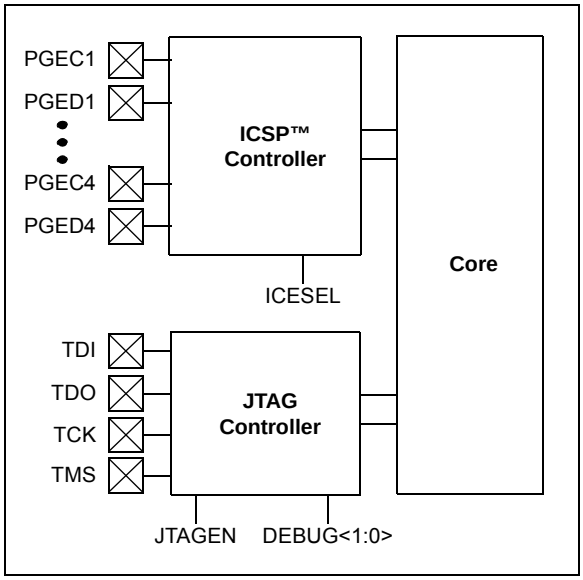
PIC32MX1XX/2XX 28/36/44-pin Family devices provide a complete range of programming and diagnostic features that can increase the flexibility of any application using them. These features allow system designers to include:

- Simplified field programmability using two-wire In-Circuit Serial Programming™ (ICSP™) interfaces
- Debugging using ICSP
- Programming and debugging capabilities using the EJTAG extension of JTAG
- JTAG boundary scan testing for device and board diagnostics

PIC32 devices incorporate two programming and diagnostic modules, and a trace controller, that provide a range of functions to the application developer.

Figure 27-2 illustrates a block diagram of the programming, debugging, and trace ports.

FIGURE 27-2: BLOCK DIAGRAM OF PROGRAMMING, DEBUGGING AND TRACE PORTS



NOTES:

TABLE 30-4: DC TEMPERATURE AND VOLTAGE SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	**Symbol**	**Characteristics**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
Operating Voltage							
DC10	VDD	**Supply Voltage (Note 2)**	2.3	—	3.6	V	—
DC12	VDR	**RAM Data Retention Voltage (Note 1)**	1.75	—	—	V	—
DC16	VPOR	**VDD Start Voltage** to Ensure Internal Power-on Reset Signal	1.75	—	2.1	V	—
DC17	SVDD	**VDD Rise Rate** to Ensure Internal Power-on Reset Signal	0.00005	—	0.115	V/μs	—

Note 1: This is the limit to which VDD can be lowered without losing RAM data.

2: Overall functional device operation at VBORMIN < VDD < VDDMIN is tested, but not characterized. All device Analog modules, such as ADC, etc., will function, but with degraded performance below VDDMIN. Refer to parameter BO10 in Table 30-11 for BOR values.

TABLE 30-32: I2Cx BUS DATA TIMING REQUIREMENTS (MASTER MODE)

AC CHARACTERISTICS				Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp			
Param. No.	**Symbol**	**Characteristics**		**Min.(1)**	**Max.**	**Units**	**Conditions**
IM10	TLO:SCL	Clock Low Time	100 kHz mode	TPB * (BRG + 2)	—	µs	—
			400 kHz mode	TPB * (BRG + 2)	—	µs	—
			1 MHz mode **(Note 2)**	TPB * (BRG + 2)	—	µs	—
IM11	THI:SCL	Clock High Time	100 kHz mode	TPB * (BRG + 2)	—	µs	—
			400 kHz mode	TPB * (BRG + 2)	—	µs	—
			1 MHz mode **(Note 2)**	TPB * (BRG + 2)	—	µs	—
IM20	TF:SCL	SDAx and SCLx Fall Time	100 kHz mode	—	300	ns	CB is specified to be from 10 to 400 pF
			400 kHz mode	20 + 0.1 CB	300	ns	
			1 MHz mode **(Note 2)**	—	100	ns	
IM21	TR:SCL	SDAx and SCLx Rise Time	100 kHz mode	—	1000	ns	CB is specified to be from 10 to 400 pF
			400 kHz mode	20 + 0.1 CB	300	ns	
			1 MHz mode **(Note 2)**	—	300	ns	
IM25	TSU:DAT	Data Input Setup Time	100 kHz mode	250	—	ns	—
			400 kHz mode	100	—	ns	
			1 MHz mode **(Note 2)**	100	—	ns	
IM26	THD:DAT	Data Input Hold Time	100 kHz mode	0	—	µs	—
			400 kHz mode	0	0.9	µs	
			1 MHz mode **(Note 2)**	0	0.3	µs	
IM30	TSU:STA	Start Condition Setup Time	100 kHz mode	TPB * (BRG + 2)	—	µs	Only relevant for Repeated Start condition
			400 kHz mode	TPB * (BRG + 2)	—	µs	
			1 MHz mode **(Note 2)**	TPB * (BRG + 2)	—	µs	
IM31	THD:STA	Start Condition Hold Time	100 kHz mode	TPB * (BRG + 2)	—	µs	After this period, the first clock pulse is generated
			400 kHz mode	TPB * (BRG + 2)	—	µs	
			1 MHz mode **(Note 2)**	TPB * (BRG + 2)	—	µs	
IM33	TSU:STO	Stop Condition Setup Time	100 kHz mode	TPB * (BRG + 2)	—	µs	—
			400 kHz mode	TPB * (BRG + 2)	—	µs	
			1 MHz mode **(Note 2)**	TPB * (BRG + 2)	—	µs	
IM34	THD:STO	Stop Condition Hold Time	100 kHz mode	TPB * (BRG + 2)	—	ns	—
			400 kHz mode	TPB * (BRG + 2)	—	ns	
			1 MHz mode **(Note 2)**	TPB * (BRG + 2)	—	ns	

Note 1: BRG is the value of the I^2C Baud Rate Generator.

2: Maximum pin capacitance = 10 pF for all I2Cx pins (for 1 MHz mode only).

3: The typical value for this parameter is 104 ns.

TABLE 30-33: I2Cx BUS DATA TIMING REQUIREMENTS (SLAVE MODE)

AC CHARACTERISTICS				Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp			
Param. No.	**Symbol**	**Characteristics**		**Min.**	**Max.**	**Units**	**Conditions**
IS10	TLO:SCL	Clock Low Time	100 kHz mode	4.7	—	μs	PBCLK must operate at a minimum of 800 kHz
			400 kHz mode	1.3	—	μs	PBCLK must operate at a minimum of 3.2 MHz
			1 MHz mode **(Note 1)**	0.5	—	μs	—
IS11	THI:SCL	Clock High Time	100 kHz mode	4.0	—	μs	PBCLK must operate at a minimum of 800 kHz
			400 kHz mode	0.6	—	μs	PBCLK must operate at a minimum of 3.2 MHz
			1 MHz mode **(Note 1)**	0.5	—	μs	—
IS20	TF:SCL	SDAx and SCLx Fall Time	100 kHz mode	—	300	ns	CB is specified to be from 10 to 400 pF
			400 kHz mode	20 + 0.1 CB	300	ns	
			1 MHz mode **(Note 1)**	—	100	ns	
IS21	TR:SCL	SDAx and SCLx Rise Time	100 kHz mode	—	1000	ns	CB is specified to be from 10 to 400 pF
			400 kHz mode	20 + 0.1 CB	300	ns	
			1 MHz mode **(Note 1)**	—	300	ns	
IS25	TSU:DAT	Data Input Setup Time	100 kHz mode	250	—	ns	—
			400 kHz mode	100	—	ns	
			1 MHz mode **(Note 1)**	100	—	ns	
IS26	THD:DAT	Data Input Hold Time	100 kHz mode	0	—	ns	—
			400 kHz mode	0	0.9	μs	
			1 MHz mode **(Note 1)**	0	0.3	μs	
IS30	TSU:STA	Start Condition Setup Time	100 kHz mode	4700	—	ns	Only relevant for Repeated Start condition
			400 kHz mode	600	—	ns	
			1 MHz mode **(Note 1)**	250	—	ns	
IS31	THD:STA	Start Condition Hold Time	100 kHz mode	4000	—	ns	After this period, the first clock pulse is generated
			400 kHz mode	600	—	ns	
			1 MHz mode **(Note 1)**	250	—	ns	
IS33	TSU:STO	Stop Condition Setup Time	100 kHz mode	4000	—	ns	—
			400 kHz mode	600	—	ns	
			1 MHz mode **(Note 1)**	600	—	ns	

Note 1: Maximum pin capacitance = 10 pF for all I2Cx pins (for 1 MHz mode only).

TABLE 30-41: CTMU CURRENT SOURCE SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions (see Note 3):2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param No.	**Symbol**	**Characteristic**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
CTMU CURRENT SOURCE							
CTMUI1	IOUT1	Base Range(1)	—	0.55	—	µA	CTMUCON<9:8> = 01
CTMUI2	IOUT2	10x Range(1)	—	5.5	—	µA	CTMUCON<9:8> = 10
CTMUI3	IOUT3	100x Range(1)	—	55	—	µA	CTMUCON<9:8> = 11
CTMUI4	IOUT4	1000x Range(1)	—	550	—	µA	CTMUCON<9:8> = 00
CTMUFV1	VF	Temperature Diode Forward Voltage(1,2)	—	0.598	—	V	TA = +25ºC, CTMUCON<9:8> = 01
			—	0.658	—	V	TA = +25ºC, CTMUCON<9:8> = 10
			—	0.721	—	V	TA = +25ºC, CTMUCON<9:8> = 11
CTMUFV2	VFVR	Temperature Diode Rate of Change(1,2)	—	-1.92	—	mV/ºC	CTMUCON<9:8> = 01
			—	-1.74	—	mV/ºC	CTMUCON<9:8> = 10
			—	-1.56	—	mV/ºC	CTMUCON<9:8> = 11

Note 1: Nominal value at center point of current trim range (CTMUCON<15:10> = 000000).

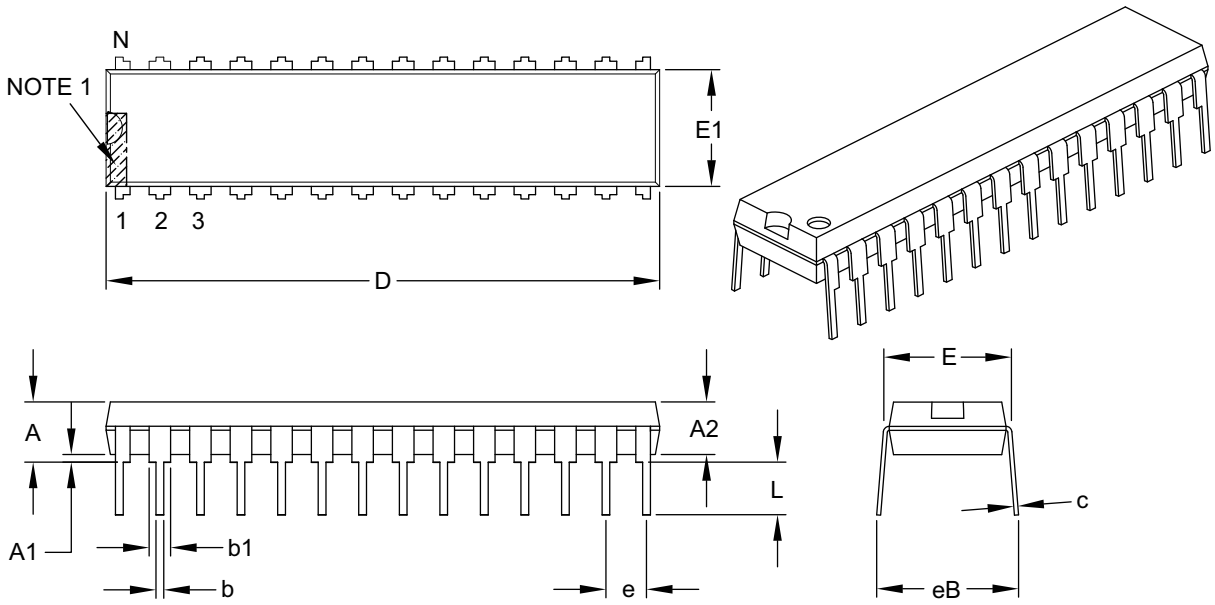
2: Parameters are characterized but not tested in manufacturing. Measurements taken with the following conditions:

- VREF+ = AVDD = 3.3V
- ADC module configured for conversion speed of 500 ksps
- All PMD bits are cleared (PMDx = 0)
- Executing a while(1) statement
- Device operating from the FRC with no PLL

3: The CTMU module is functional at VBORMIN < VDD < VDDMIN, but with degraded performance. Unless otherwise stated, module functionality is tested, but not characterized.

28-Lead Skinny Plastic Dual In-Line (SP) – 300 mil Body [SPDIP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		INCHES		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		28	
Pitch	e		.100 BSC	
Top to Seating Plane	A	–	–	.200
Molded Package Thickness	A2	.120	.135	.150
Base to Seating Plane	A1	.015	–	–
Shoulder to Shoulder Width	E	.290	.310	.335
Molded Package Width	E1	.240	.285	.295
Overall Length	D	1.345	1.365	1.400
Tip to Seating Plane	L	.110	.130	.150
Lead Thickness	c	.008	.010	.015
Upper Lead Width	b1	.040	.050	.070
Lower Lead Width	b	.014	.018	.022
Overall Row Spacing §	eB	–	–	.430

Notes:

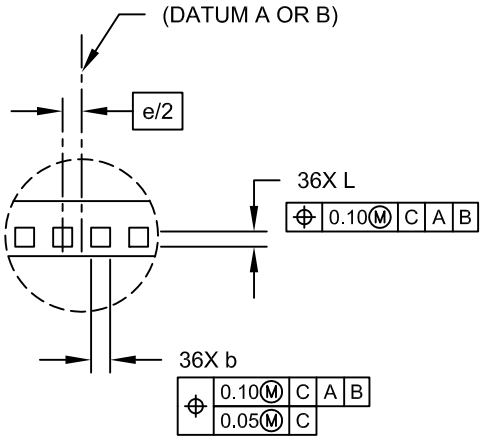
1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. § Significant Characteristic.
3. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" per side.
4. Dimensioning and tolerancing per ASME Y14.5M.

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

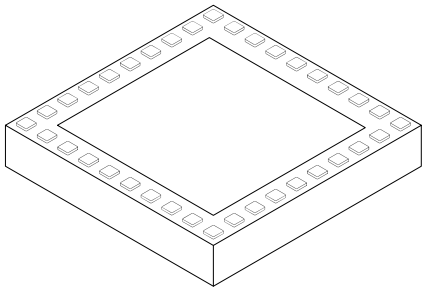
Microchip Technology Drawing C04-070B

36-Terminal Very Thin Thermal Leadless Array Package (TL) – 5x5x0.9 mm Body with Exposed Pad [VTLA]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



DETAIL A



Units		MILLIMETERS		
Dimension	Limits	MIN	NOM	MAX
Number of Pins	N		36	
Number of Pins per Side	ND		10	
Number of Pins per Side	NE		8	
Pitch	e		0.50 BSC	
Overall Height	A	0.80	0.90	1.00
Standoff	A1	0.025	-	0.075
Overall Width	E		5.00 BSC	
Exposed Pad Width	E2	3.60	3.75	3.90
Overall Length	D		5.00 BSC	
Exposed Pad Length	D2	3.60	3.75	3.90
Contact Width	b	0.20	0.25	0.30
Contact Length	L	0.20	0.25	0.30
Contact-to-Exposed Pad	K	0.20	-	-

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package is saw singulated.
3. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.
REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-187C Sheet 2 of 2